

ABSTRACT

The present invention provides an insoluble-anode plating equipment that can uniformly and continuously perform a favorable copper plating process by suppressing a fluctuation in copper concentration in the cathode plating solution as much as possible, and by suppressing consumption of additives contained in the cathode plating solution. The insoluble-anode plating equipment provided with a separating membrane includes a copper oxide powder supply unit configured to supply copper oxide powder to a control tank together with a carrier gas via a supply tube having an ability to remove static electricity, wherein an upper lid body of the control tank is provided with a powder supply cylinder having an ability to remove static electricity, and having a leading end disposed in a vicinity of a liquid surface of a cathode plating solution stored in the control tank, and a supply tube is connected to the powder supply cylinder.